附件3

《化合物半导体芯片工厂设计规范》征求意见表

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| 姓名 | |  | 职务 |  | 单位 |  |
| 联系电话 | |  | 邮政编码 |  | 通信地址 |  |
| E-mail | |  | 传真 |  |
| 序号 | 条文  编号 | 原条文 | | 修改意见 | | |
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（纸面不敷，可另增页）

通信地址：北京市西四环北路160号B座中国电子工程设计院有限公司

联 系 人：薛瑞

电子邮箱：xuerui@ceedi.cn

联系电话：010-88193969 18010156467